

What is the right LED epiwafer strategy for mass production of micro LED displays?

Burkhard Slischka, CEO and co-founder ALLOS Semiconductors
International Micro LED Display Conference 2019, Taipei, 29th August 2019



ALLOS
Semiconductors





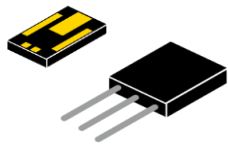
**No need to take photos – write me to get your copy
bs@allos-semiconductors.com**

1. Introduction to ALLOS Semiconductors

- 2. How to make micro LED displays a mass market reality?
- 3. Manufacturing readiness of ALLOS' epiwafer technology
- 4. How to work with ALLOS

ALLOS develops and offers GaN-on-Si technology, which is the key enabler for three fast-growing markets

High power electronics (HPE)



GaN-on-Si enables more energy-efficient, less complex and smaller high power electronic (HPE) devices from existing silicon lines

Radio frequency devices (RF)



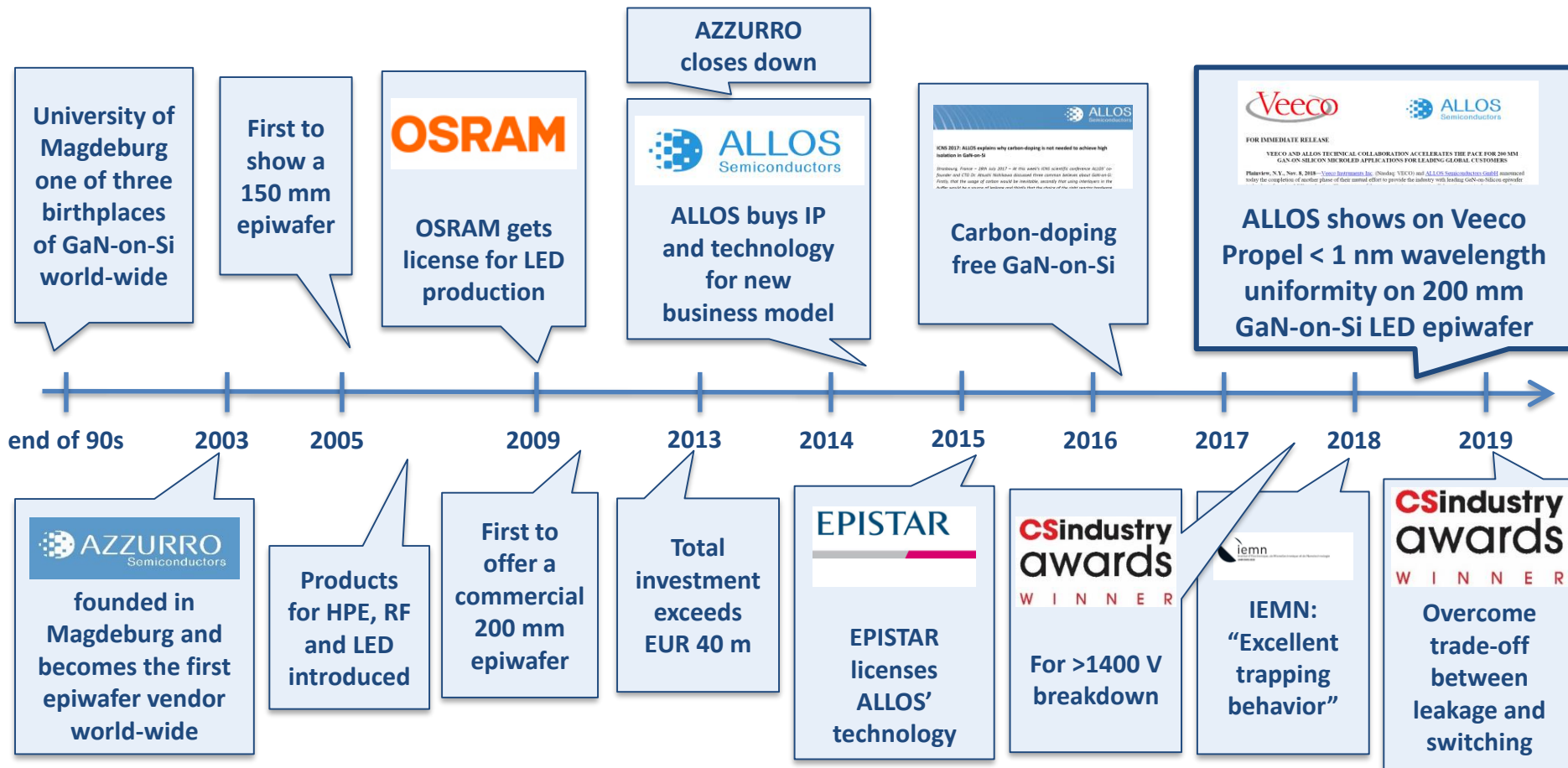
GaN-on-Si provides higher performance, smaller, more energy efficient and lower cost RF devices, for 5G base-stations, smart-phones, CATV, IoT and other RF applications

Micro LED / LED



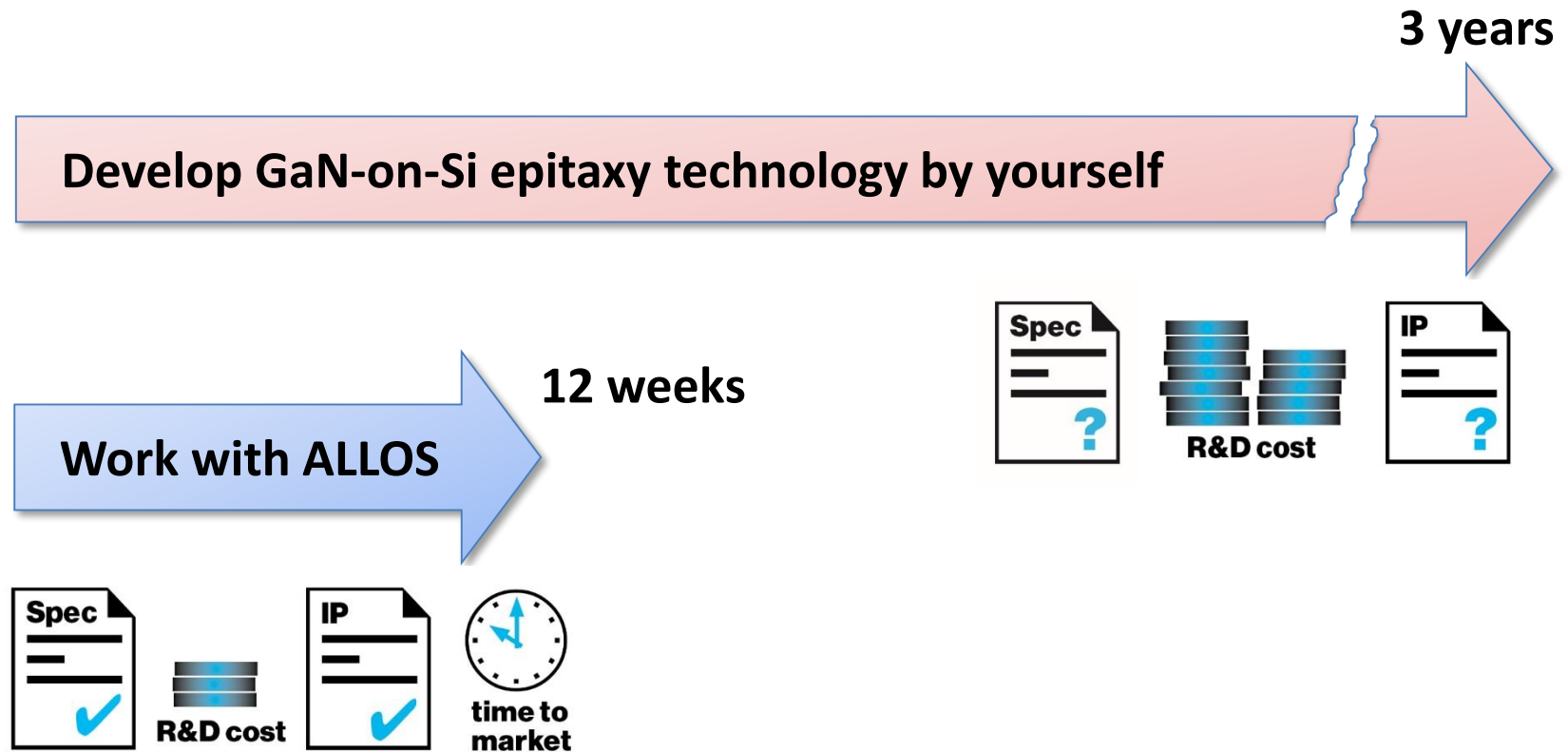
Only GaN-on-Si allows super-uniform, large diameter, CMOS-compatible 1 bin® epiwafers needed for large-scale micro LED display production

ALLOS* is a leader in GaN-on-Si with 15 years track-record



* ALLOS and its predecessor-company AZZURRO

Technology Transfer is the core of our business offer



1. Introduction to ALLOS Semiconductors
2. How to make micro LED displays a mass market reality?
3. Manufacturing readiness of ALLOS' epiwafer technology
4. How to work with ALLOS

Micro LED displays: Big advantages over LCD and OLED rivals...



- ✓ Perfect black, brightness and contrast
- ✓ Displays readable even in sunlight
- ✓ High resolution and pixel density
- ✓ More accurate and vivid colors
- ✓ Longer battery runtime
- ✓ Fast refresh rates
- ✓ Wide viewing angles
- ✓ Curved and flexible backplanes
- ✓ Integration of sensors within display
- ✓ Long lifetime, environmental stability
- ✓ Can be integrated into window glass, fabric, building structures or other materials

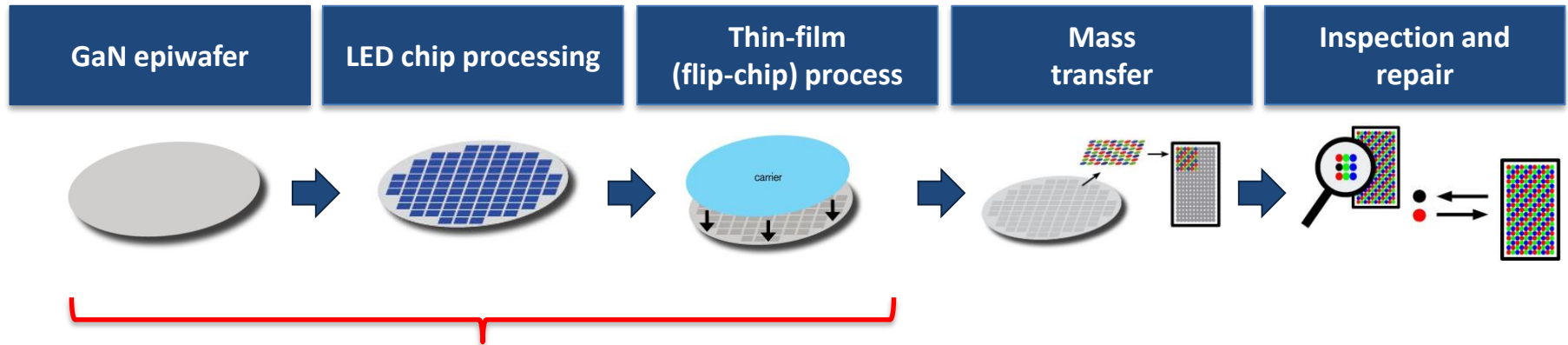
Source:  VIOLE
Développement

... but one big challenge prevents mass market break-through



➡ **Cost**

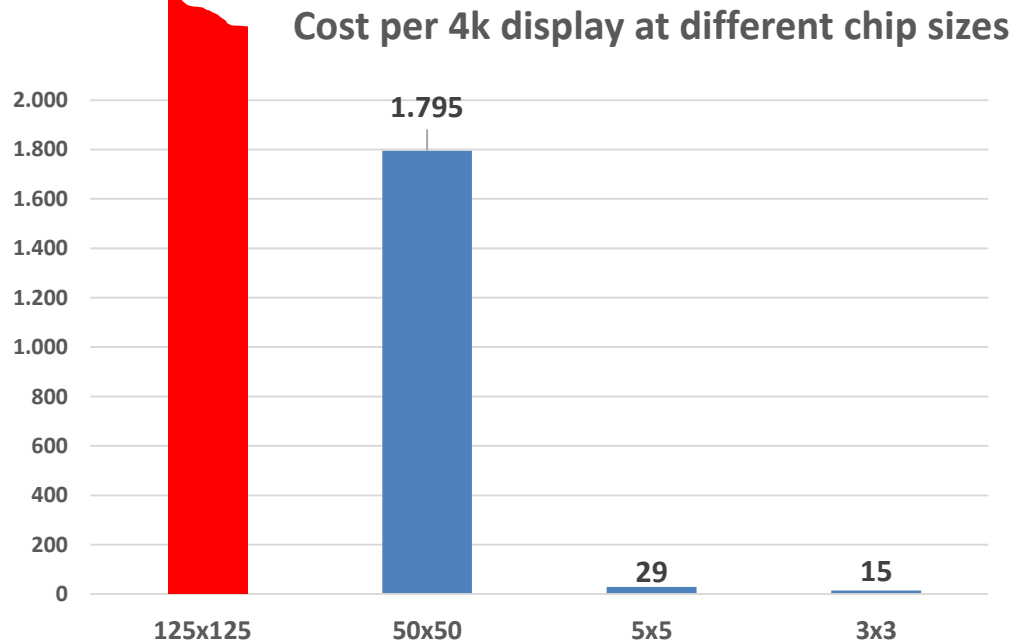
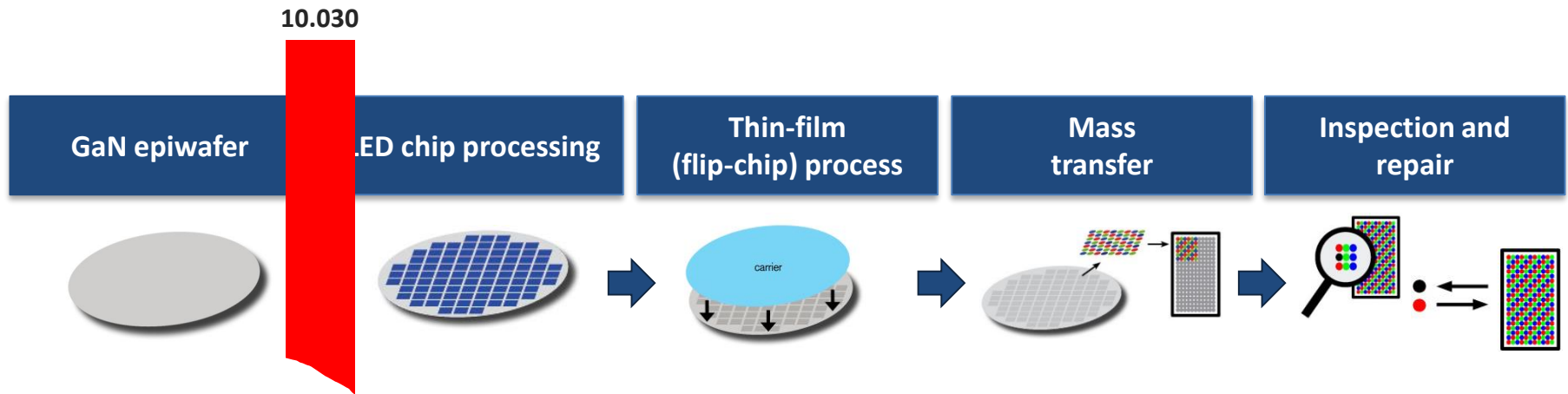
Where is this cost problem coming from? (1)



COST ESTIMATE 200 mm	(USD)
Epi cost benchmark LED industry	232,50
Processing cost benchmark 200 mm foundry	90,00
Thin-film cost benchmark	30,00
Sum benchmark cost	<u>352,50</u>
100% safety margin for additional tools, initially higher effort, risk, etc.	352,50
Realistic cost target for processed wafer*	<u>705,00</u>

* Source: ALLOS' research; assuming volume production; cost estimate based on blue LED chips on 200 mm wafer ready to be transferred; assuming same area cost for green and red epiwafers

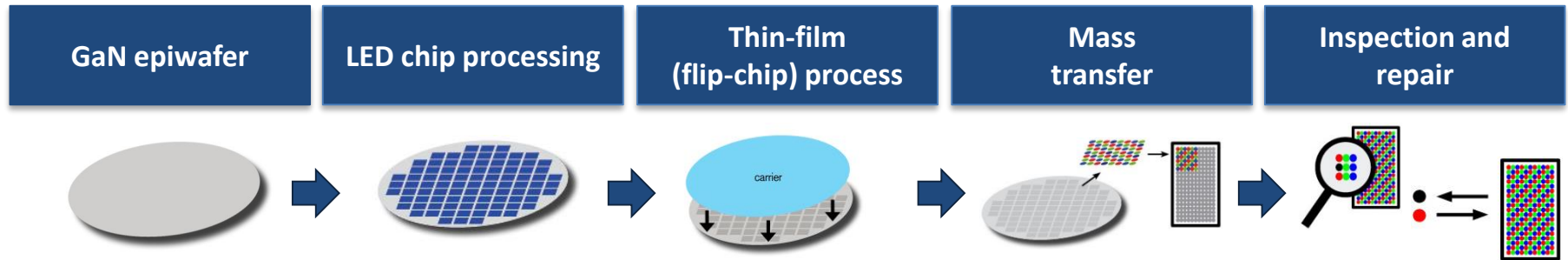
Where is this cost problem coming from? (2)



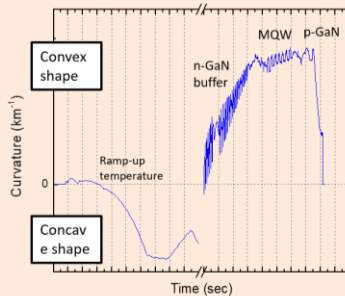
Chip sizes in μm ; see previous slide for assumptions

- Even with 100 % safety margin processed micro LED wafers are cost competitive
- Increased usage of smaller chips will drive down cost
- The real challenge is yield
- ...and resulting cost in test, transfer and repair

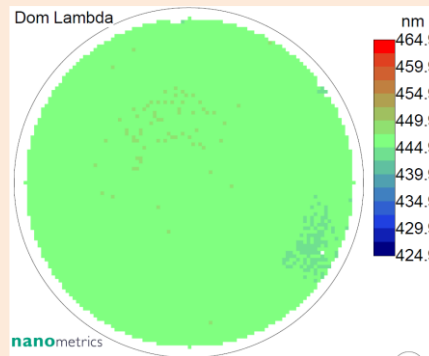
How to make micro LED displays a mass market reality? (1)



Control growth conditions for LED epiwafer growth

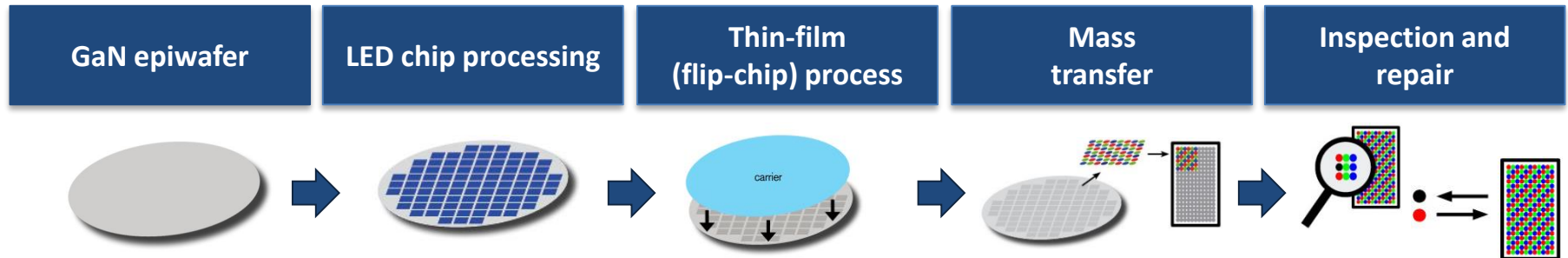


1-bin[®] wavelength uniformity



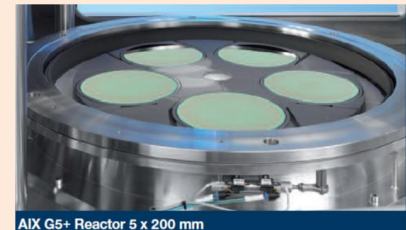
Maximize yield and save cost in all later production steps

How to make micro LED displays a mass market reality? (2)



Move to larger epiwafer sizes to save cost along the entire value chain

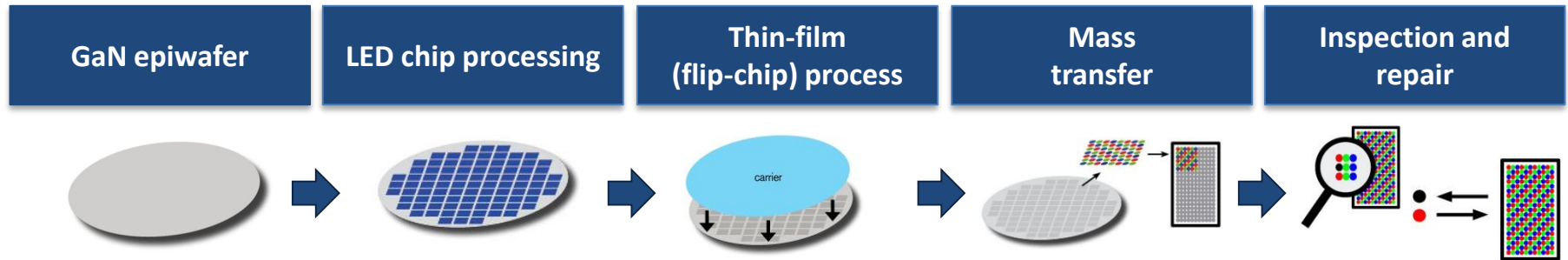
- Better reactor area utilization on most multi-wafer chamber reactors
- Use latest generation single-wafer chamber reactors for 1-bin® wavelength uniformity
- Biggest cost effects are realized at LED chip processing and thin-film processing



34 % better area utilization for 200 mm vs. 100 mm on G5+

For GaN-on-Si 200 mm is already available, path to 300 mm GaN-on-Si is open

How to make micro LED displays a mass market reality? (3)



High processing requirements for micro LEDs

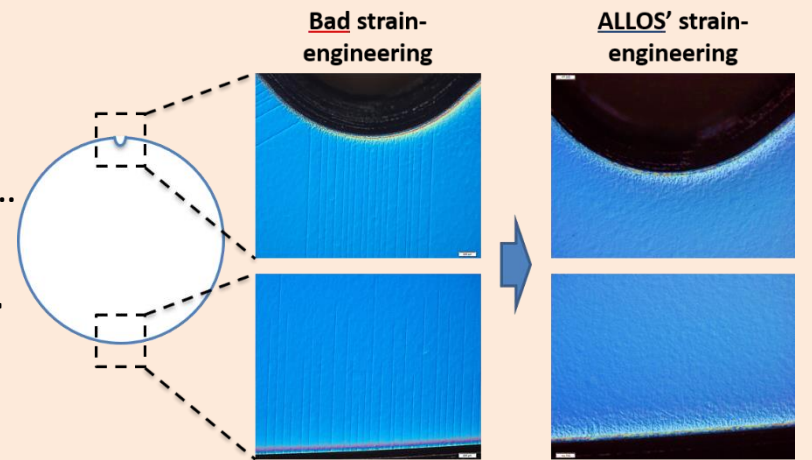
- Precision, processing resolution, particles, etc.

Consider new sourcing models

- Either huge investments for dedicated new fabs...
- Or partner with e.g. low-cost CMOS foundries

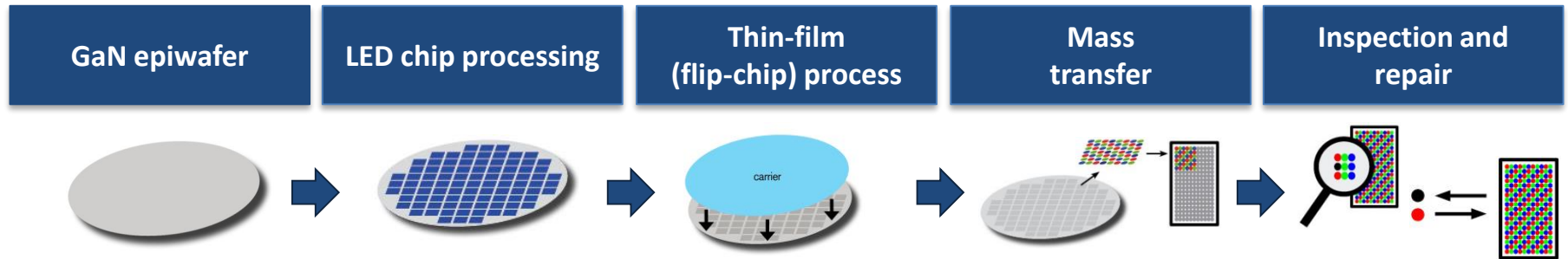
Ensure that epiwafers meet requirements for low-cost and high yield processing lines

- Wafer cleanliness, thickness, no breakage, etc.
- Minimal wafer bow
- Large wafer diameter (200 or 300 mm)



ALLOS' 200 mm LED epiwafers crack-free even at the edge

How to make micro LED displays a mass market reality? (4)



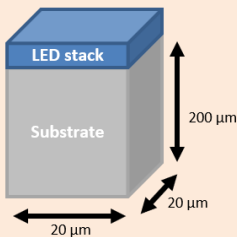
Micro LED require thin-film processes

Easy thinning of GaN-on-Si with standard tools

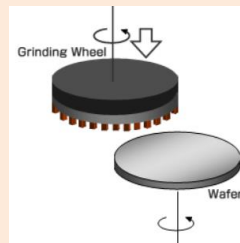
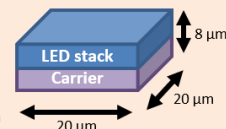
Bonding requires super-flat wafers

Wafer size match for monolithically integrated designs

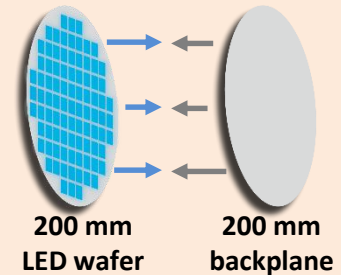
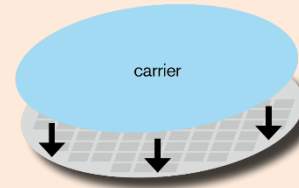
Conventional lateral LED design



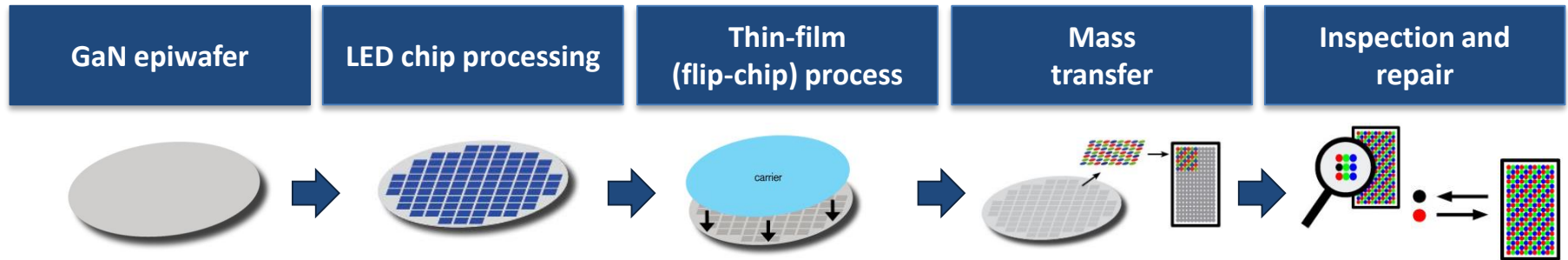
Thin-film LED



© Disco



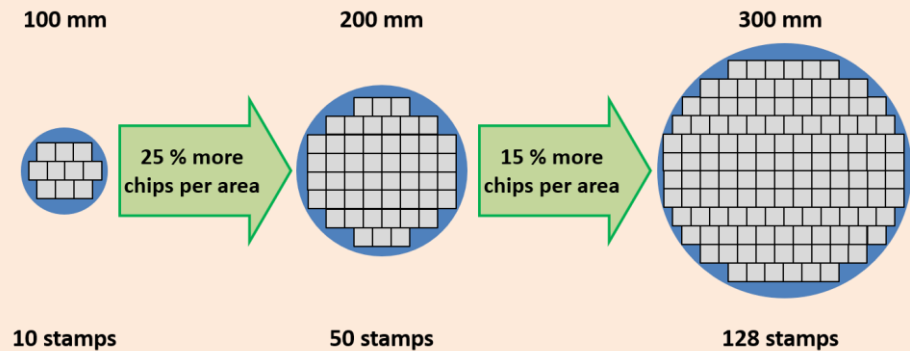
How to make micro LED displays a mass market reality? (5)



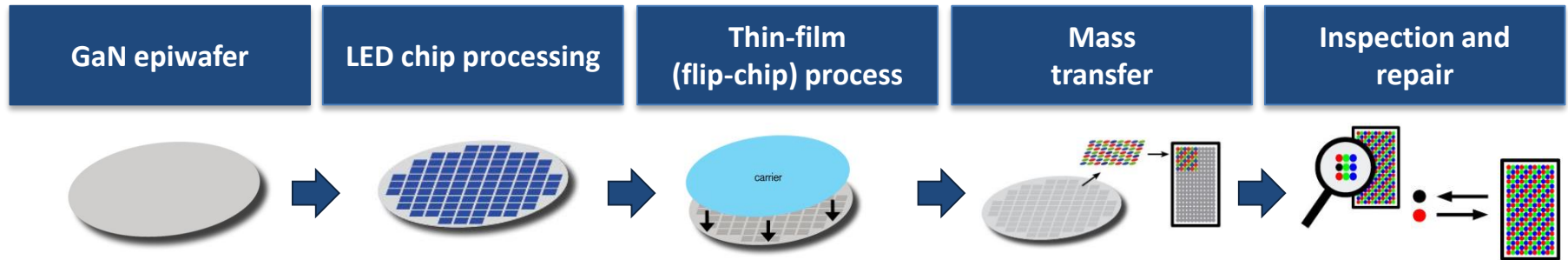
Multiple mass transfer methods have been already demonstrated

- Pick and place takes too long
- Binning is not an option
- All methods work with GaN-on-Si LED epiwafers

Transfer stamp based methods all benefit from larger epiwafers



How to make micro LED displays a mass market reality? (6)



Perfect displays required

- Consumers do not accept even one bad pixel
- Even at Six Sigma level 2,488 chips have to be repaired on a 4K display
- But to test and sort each of 25 million sub-pixels before transfer is very expensive

Relevant yield*	... equals amount of chips failing
90.00000 %	2,488,320.00
95.00000 %	1,244,160.00
99.00000 %	248,832.00
99.90000 %	24,883.2
99.99000 %	2,488.32
99.99900 %	248.83
99.99990 %	24.88
99.99999 %	2.49

Two major approaches to solve this dilemma

A. "Blind printing"

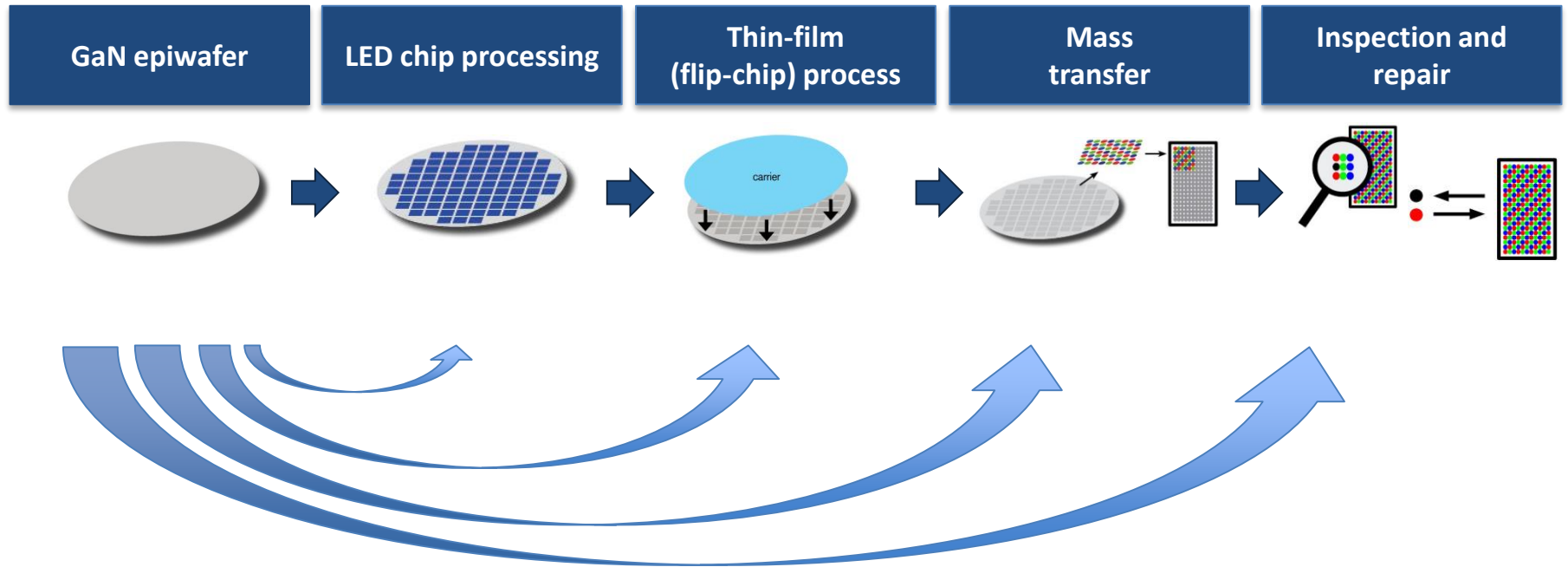
- No testing, just transfer and "test" on display
- Repair on display (e.g. using redundancies)

B. "Maximize % of KGD"

- In-line testing
- Transfer only known good dies / segments
- No or minimal repair needed

Both become cost-efficient only with super uniform epiwafer material

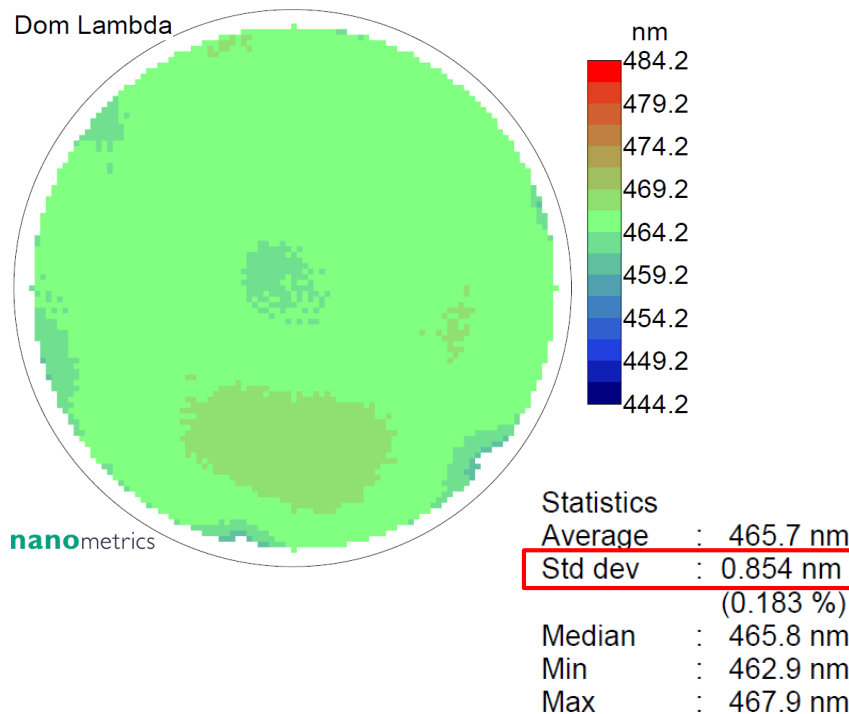
1-bin[®] epiwafer properties can maximize yield and save cost in all later production steps



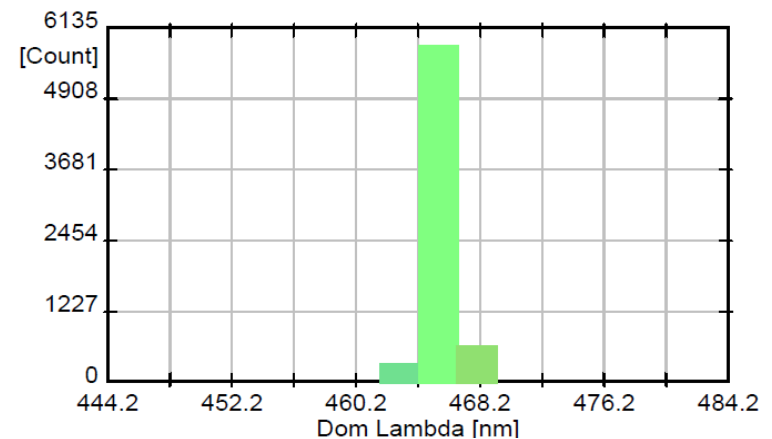
Epiwafer uniformity and quality is crucial for yield and cost in all later steps

1. Introduction to ALLOS Semiconductors
2. How to make micro LED displays a mass market reality?
3. Manufacturing readiness of ALLOS' epiwafer technology
4. How to work with ALLOS

Record-breaking emission uniformity < 1 nm is achieved on 200 mm GaN-on-Si micro LED epiwafer



Dom Lambda Histogram



85.3 % in 2.5 nm bin
Min-max = +/- 2.5 nm

Result from customer project on Veeco Propel in summer 2018

The technology has excellent reproducibility (PL mapping)

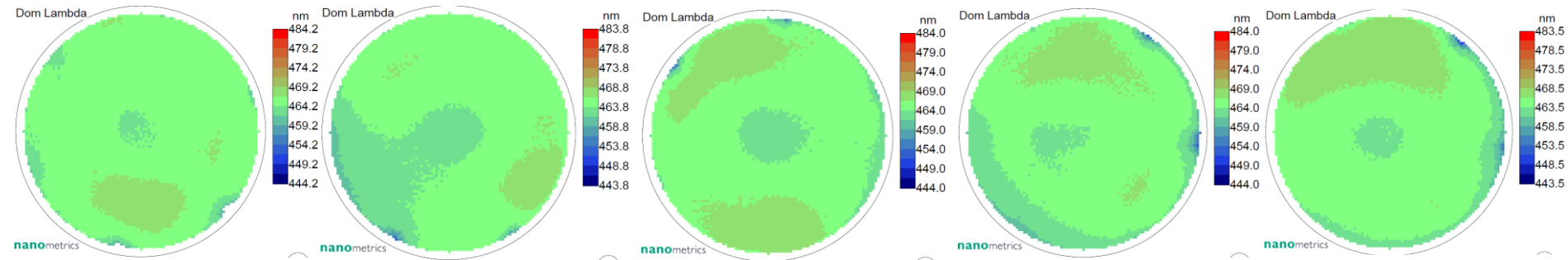
LED run#1

LED run#2

LED run#3

LED run#4

LED run#5



Statistics
 Average : 465.7 nm
 Std dev : 0.854 nm
 (0.183 %)
 Median : 465.8 nm
 Min : 462.9 nm
 Max : 467.9 nm
 10% cutoff : 464.5 nm
 25% cutoff : 465.1 nm
 75% cutoff : 466.2 nm
 90% cutoff : 466.7 nm

Statistics
 Average : 464.7 nm
 Std dev : 1.290 nm
 (0.278 %)
 Median : 465.0 nm
 Min : 460.6 nm
 Max : 467.2 nm
 10% cutoff : 462.9 nm
 25% cutoff : 463.8 nm
 75% cutoff : 465.6 nm
 90% cutoff : 466.2 nm

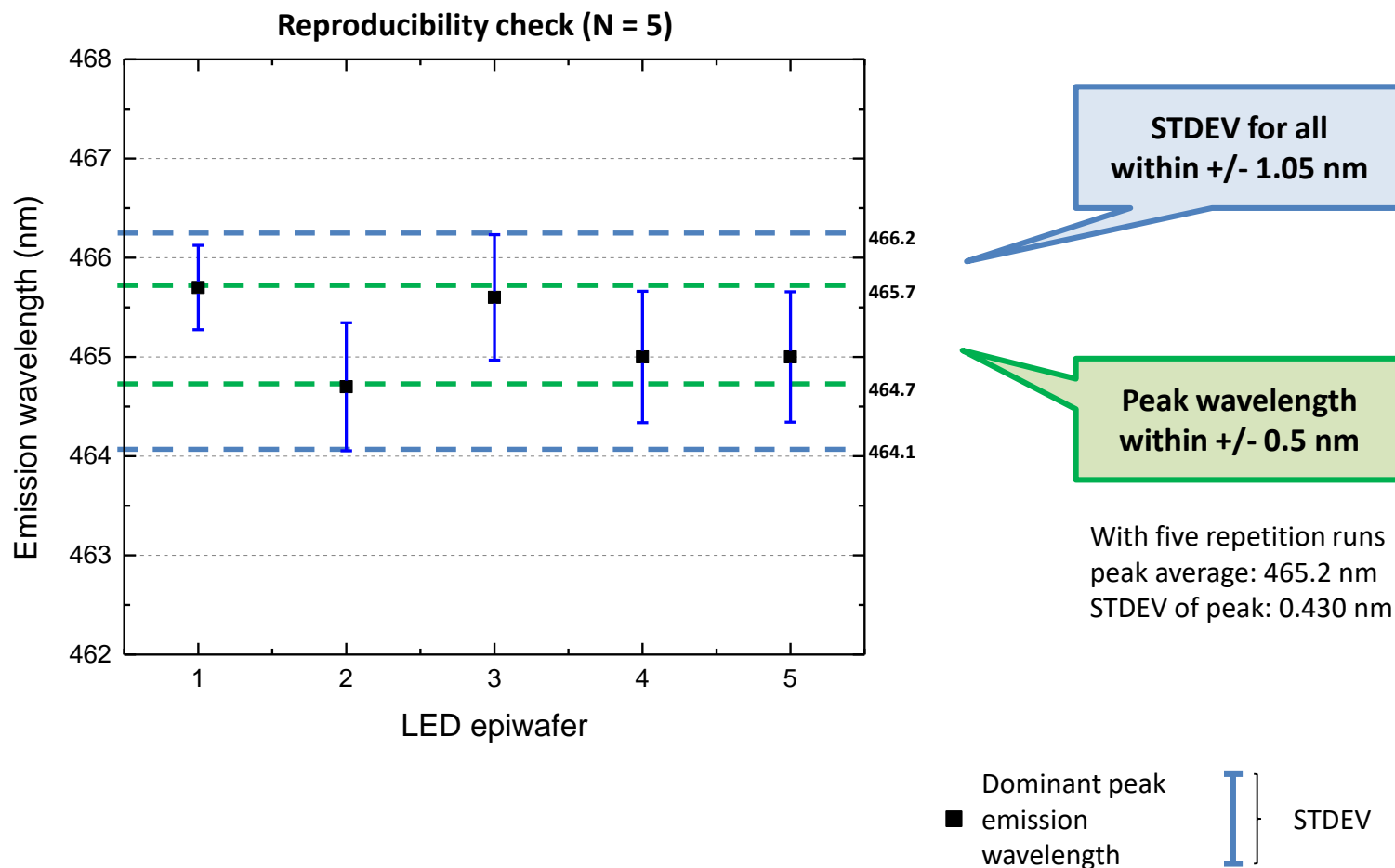
Statistics
 Average : 465.6 nm
 Std dev : 1.262 nm
 (0.271 %)
 Median : 465.6 nm
 Min : 461.7 nm
 Max : 468.4 nm
 10% cutoff : 464.0 nm
 25% cutoff : 464.6 nm
 75% cutoff : 466.5 nm
 90% cutoff : 467.3 nm

Statistics
 Average : 465.0 nm
 Std dev : 1.323 nm
 (0.284 %)
 Median : 465.2 nm
 Min : 460.6 nm
 Max : 467.4 nm
 10% cutoff : 463.3 nm
 25% cutoff : 464.2 nm
 75% cutoff : 466.1 nm
 90% cutoff : 466.6 nm

Statistics
 Average : 465.0 nm
 Std dev : 1.314 nm
 (0.283 %)
 Median : 465.0 nm
 Min : 460.5 nm
 Max : 467.8 nm
 10% cutoff : 463.3 nm
 25% cutoff : 464.2 nm
 75% cutoff : 465.8 nm
 90% cutoff : 466.9 nm

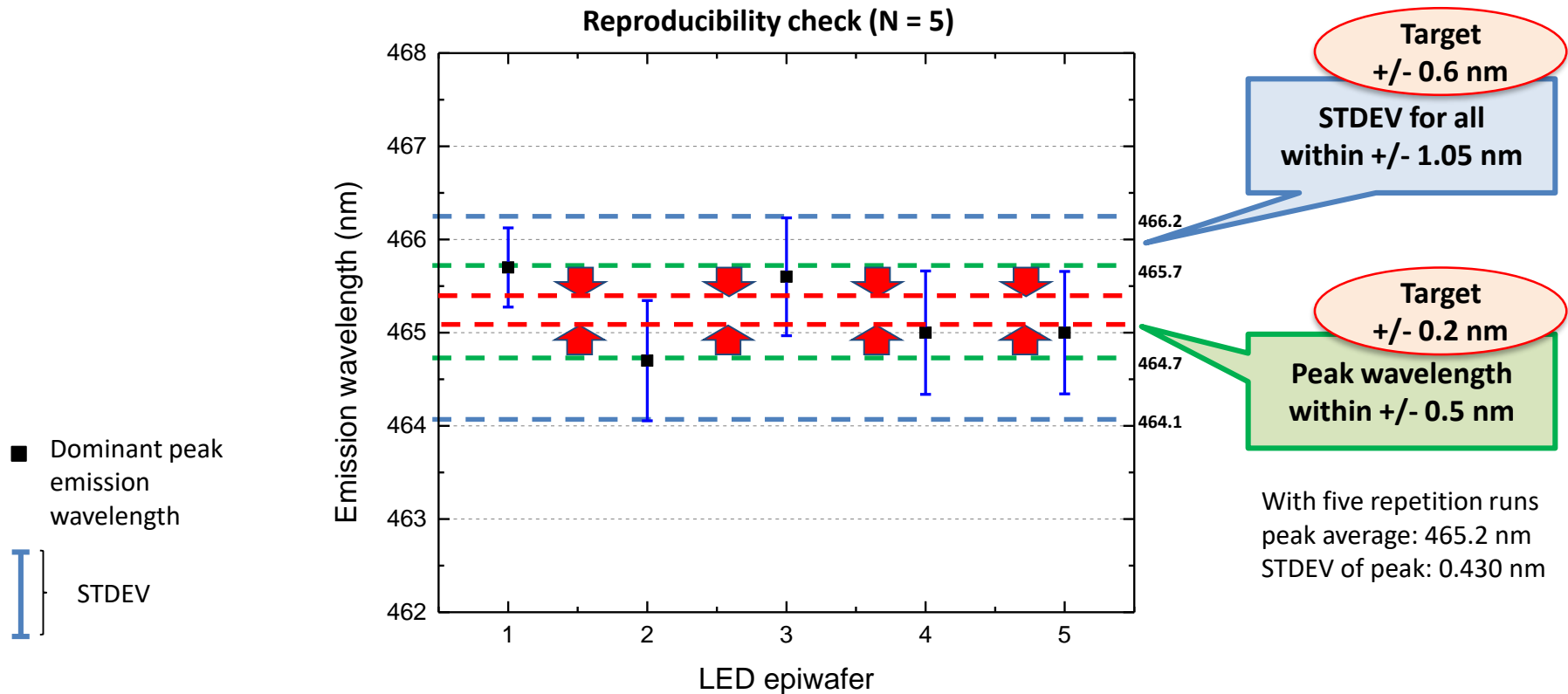
Result from customer project using the same recipe on Veeco Propel in summer 2018

Peak emission wavelength is controlled within ± 0.5 nm



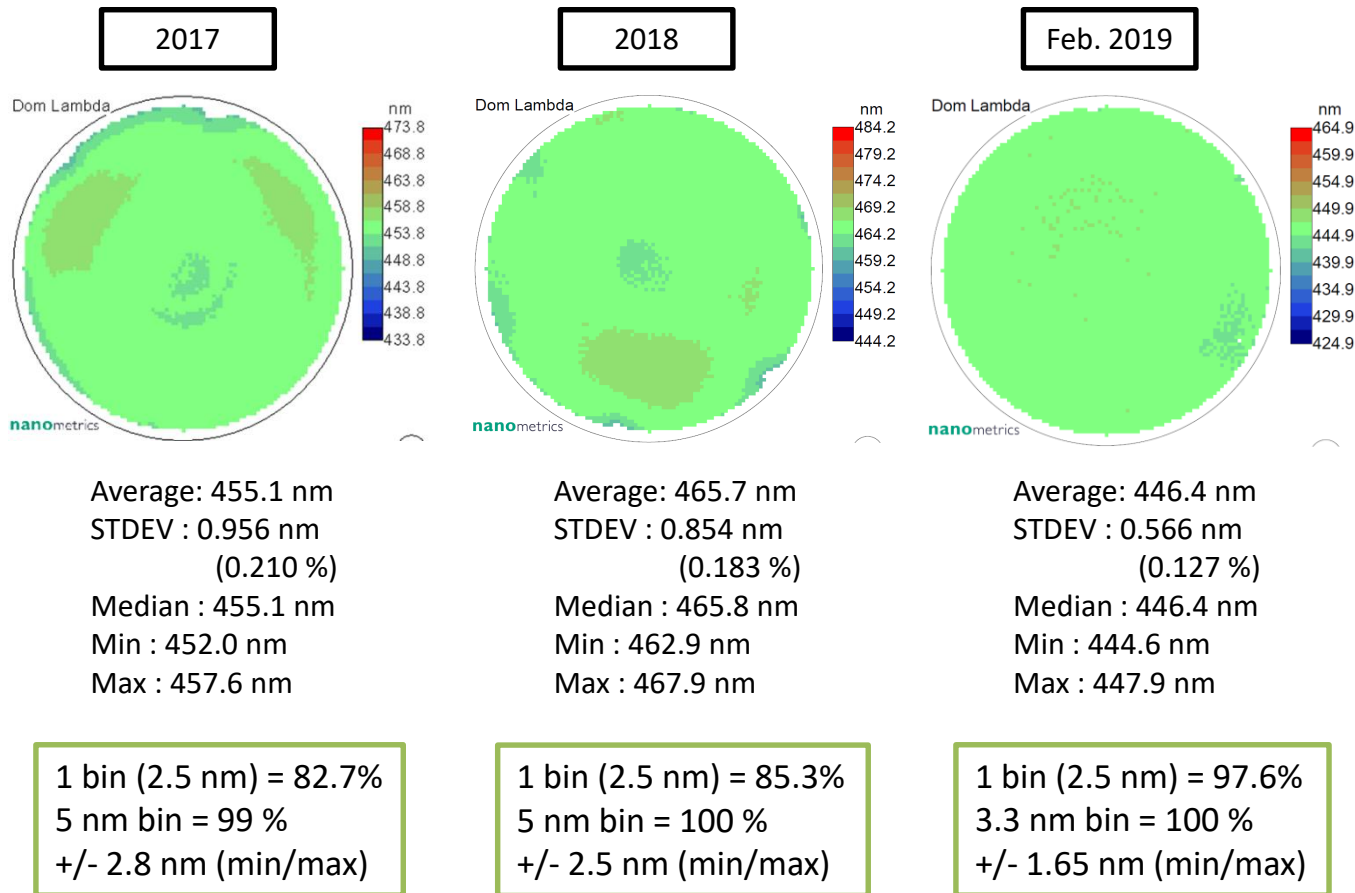
Result from customer project using the same recipe on Veeco Propel in summer 2018

...with a development target of ± 0.2 nm



Result from customer project using the same recipe on Veeco Propel in summer 2018

Outlook: Continued work shows more world record improvements for wavelength uniformity approaching the goal of +/- 1 nm



Project stage 2017: Achieving leading uniformity for 200 mm LED epiwafers (irrespective of substrate material)

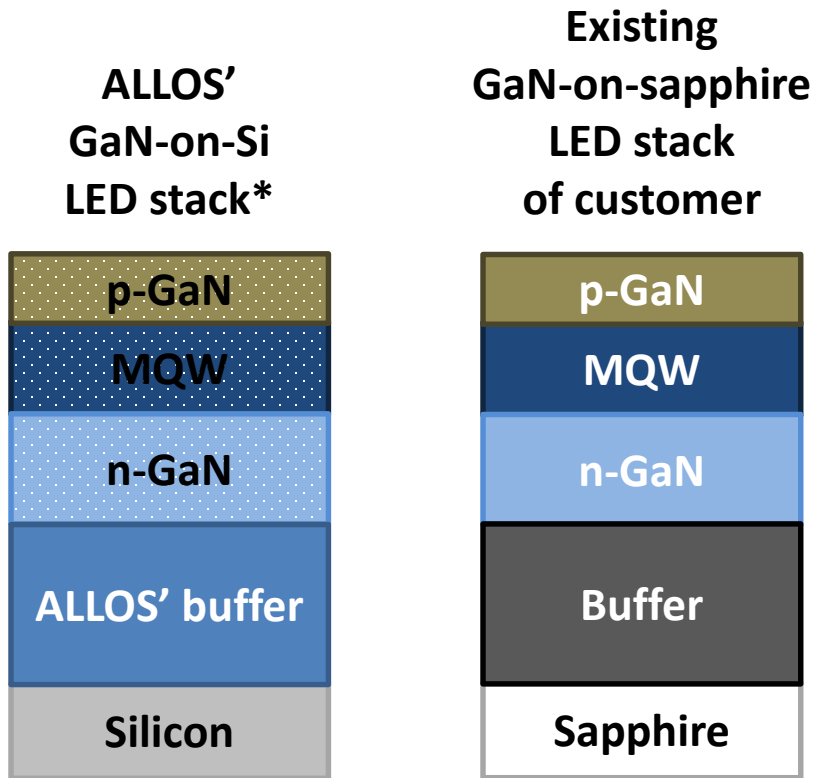
Project stage 2018: Successfully achieving all needed production parameters at the same time with excellent wafer-to-wafer reproducibility

Project stage beginning of 2019: The current project focus is on further advancing the wavelength uniformity towards a true 1 bin® objective (+/- 1 nm); shown are intermediate results

Next will be work on achieving the new leading uniformity results with all production-relevant performance elements while guaranteeing excellent reproducibility ("made for manufacturability").

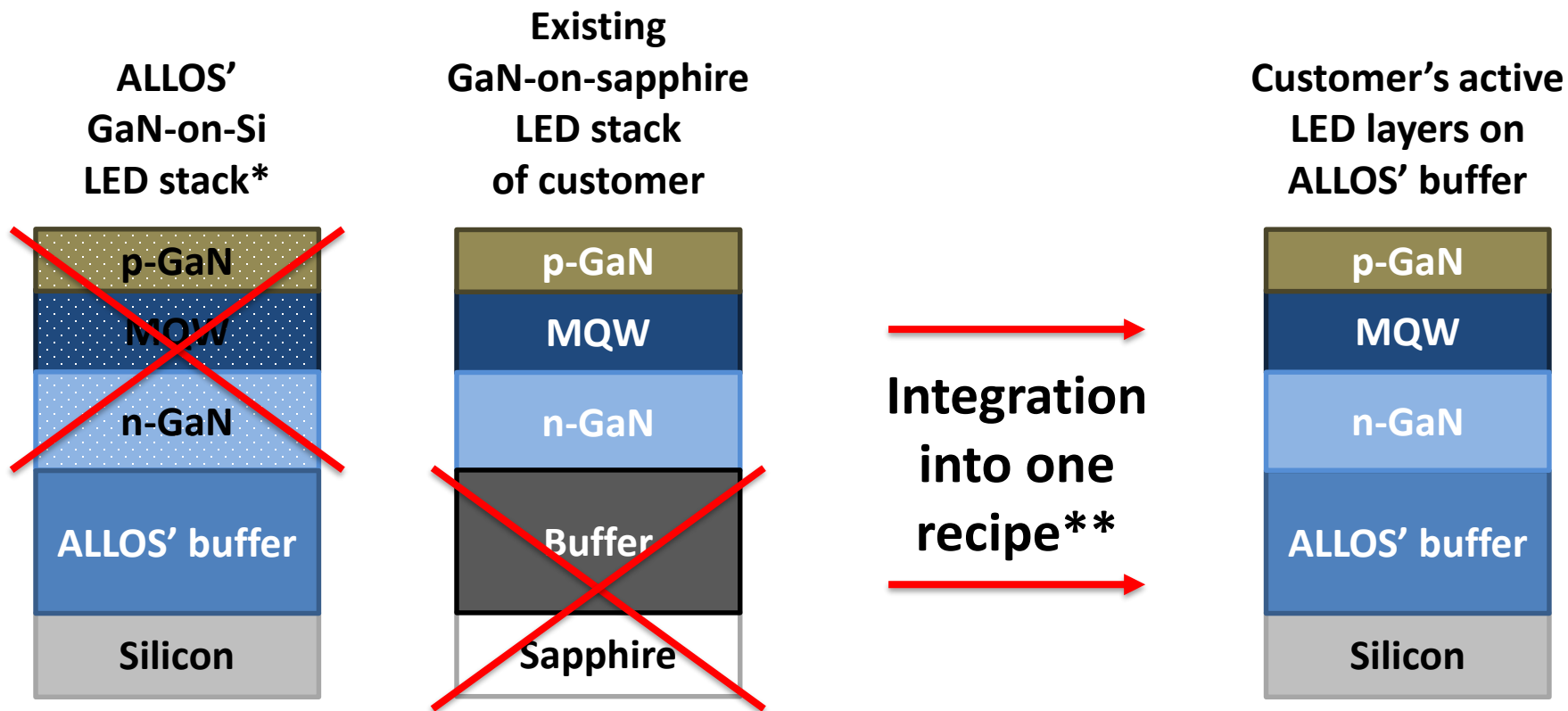
Result from customer project on Veeco Propel

With only a few epi runs any existing active LED layer structure can be integrated on ALLOS' GaN-on-Si buffer



* Transferred to customer in Technology Transfer project

With only a few epi runs any existing active LED layer structure can be integrated on ALLOS' GaN-on-Si buffer



* Transferred to customer in Technology Transfer project

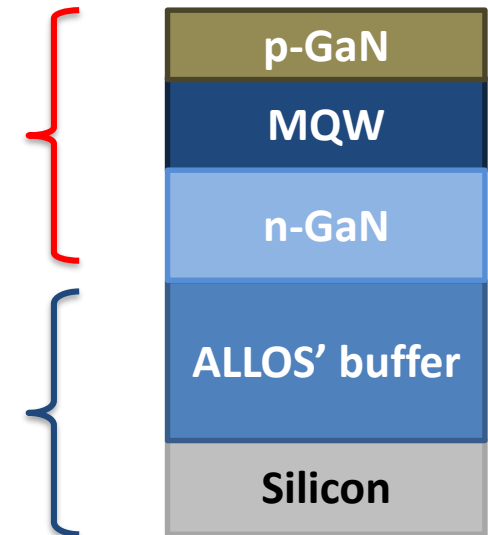
** By either joint team with ALLOS or independently by customer

...allowing the customer to benefit from the best of both technology sets

- Same performance (brightness, efficiency) on GaN-on-Si as on GaN-on-sapphire
- Existing IP protection
- Preserve learnings for LED design / epi / processing interaction

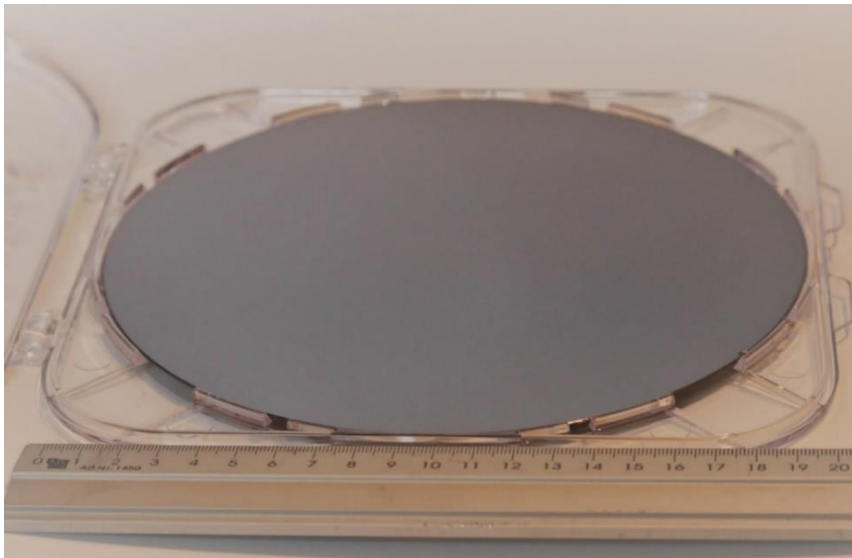
- Industry-leading GaN-on-Si performance with >15 years' of technology development background
- Best wavelength uniformity (1-bin[®])
- Large diameter, flat and CMOS-ready epiwafer

**Customer's active
LED layers on
ALLOS' buffer**



ALLOS' GaN-on-Si epiwafer fulfils all requirements for micro LED display mass production at the same time

200 mm GaN-on-Si epiwafer of ALLOS for micro LED



1 bin® wavelength uniformity



Existing MQW from on-sapphire can be easily integrated



Best GaN-on-Si crystal quality in the industry

- Same low defect level as on GaN-on-sapphire: TDD $\sim 2 \times 10^8 \text{ cm}^{-2}$
- Enables excellent LED performance



Large diameter and CMOS-ready

- 100 to 200 mm, next 300 mm
- 30 μm bow for 725 μm thickness at 200 mm
- No cracks, no residual strain



1. Introduction to ALLOS Semiconductors
2. How to make micro LED displays a mass market reality?
3. Manufacturing readiness of ALLOS' epiwafer technology
4. How to work with ALLOS

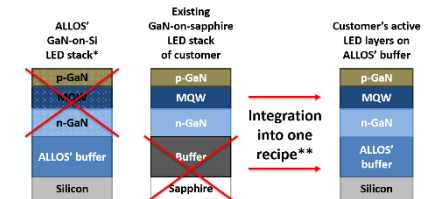
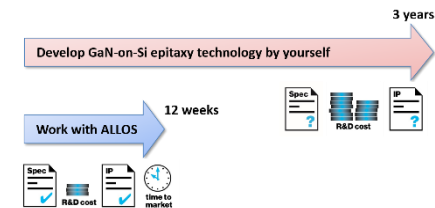
Proposed steps of working with ALLOS

Step 1: Purchase sample package and evaluate ALLOS' LED epiwafers

Step 2: Agree license and transfer ALLOS' technology to your* reactor

Step 3: Integrate your* light emitting epi-structure (optional)

Step 4: Optimize epi-stack for micro LED volume manufacturing (optional)



* Your or your partner's

Summary

- To become ready for volume production of micro LEDs the problem of insufficient yield needs to be solved
- Emission wavelength uniformity is the biggest single driver to achieve that objective
- The right (large diameter, high crystal quality, CMOS-ready) GaN-on-Si epiwafer technology can further enable cost savings in all following production steps
- ALLOS offers its GaN-on-Si technology for licensing and technology transfer and is open to work with you in your long-term projects

CSindustry awards

W I N N E R

2018 and 2019



bs@allos-semiconductors.com



[Burkhard_Slischka](#)

ALLOS Semiconductors GmbH

Burkhard Slischka, Co-founder and CEO
Breitscheidstrasse 78
01237 Dresden, Germany

Office: +49-351-212 937-10
Fax: +49-351-212 937-99

Visit us

<http://www.allos-semiconductors.com>

Follow us

<https://www.linkedin.com/company/allos-semiconductors-gmbh>
<https://twitter.com/ALLOSsemi>